

Sub-Wavelength Holographic Lithography (SWHL) for Fabrication IC & MEMS Topologies on Non-Planar Surfaces by Single Exposure

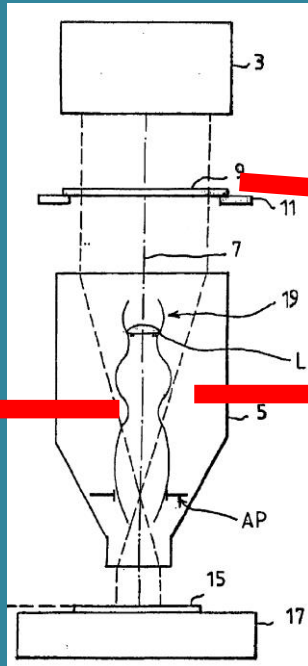
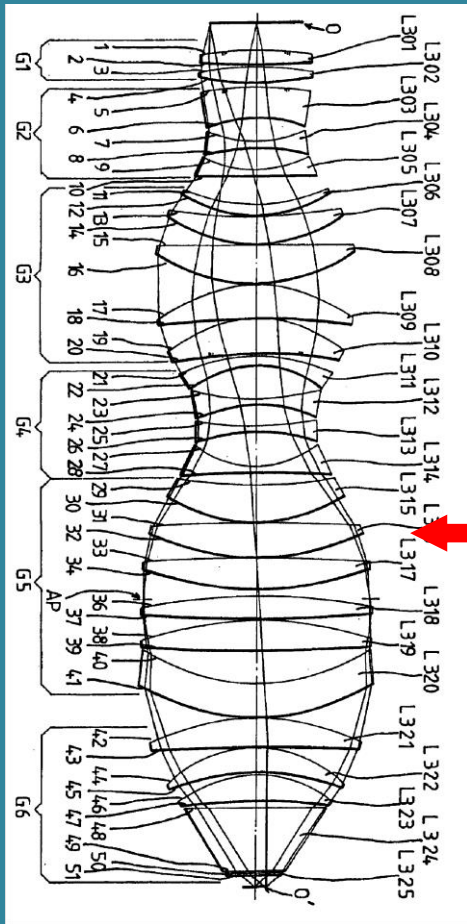
NANOTECH SWHL

39th MNE, 16-19.09.2013, London

EXECUTIVE SUMMARY

- SWHL uses newly developed mathematical apparatus that made possible digital synthesis of SWHM for aerial images of IC & MEMS topologies with CD's $\approx \lambda/2$.
- SWHL is suitable for all range of technologies nodes covered by DUVL and even for smaller CD's using coherent light sources with a shorter wavelength
- SWHM combines main functions of a mask and projection lens, which allows to have radically simple optical scheme and significantly reduce the requirements to the quality of optical elements.
- SWHL allows during of SWHM 's manufacturing avoid of technologically complex operations using instead of PS and OPC their virtual counterparts HoloPS and HoloOPC.
- Aerial images of IC & MEMS topologies are not sensitive to SWHM local defects. Because of that SWHM has an unlimited (almost) lifetime and does not need any regular control and maintenance.
- SWHL is a new, alternative low cost approach to lithography and cut your costs for:
 - Masks - up to factor of 10
 - Steppers - up to factor of 4.

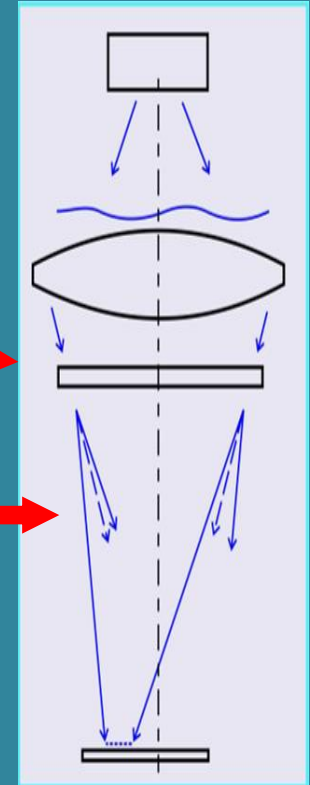
SIMPLE AND MORE EFFICIENT OPTICAL SCHEME



Exposure stage at traditional projective lithography
 Carl Zeiss Patent, US6788387, 2004

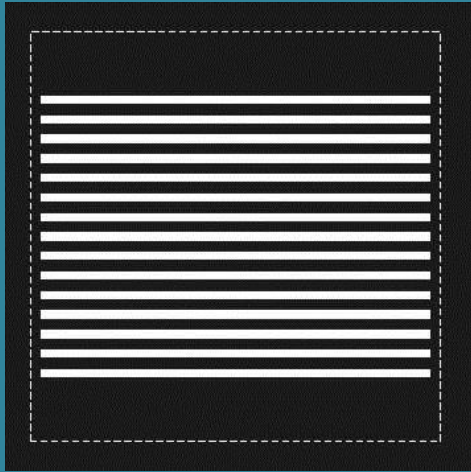
Traditional mask is replaced with a hologram (Sub-wavelength Holographic Mask - SWHM)

No Projection Lens used

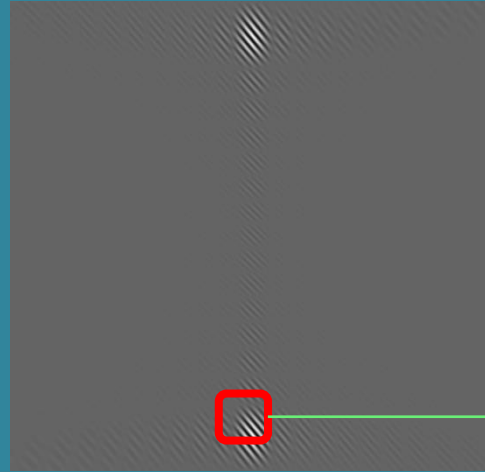


Exposure stage at sub-wavelength holographic lithography (SWHL)

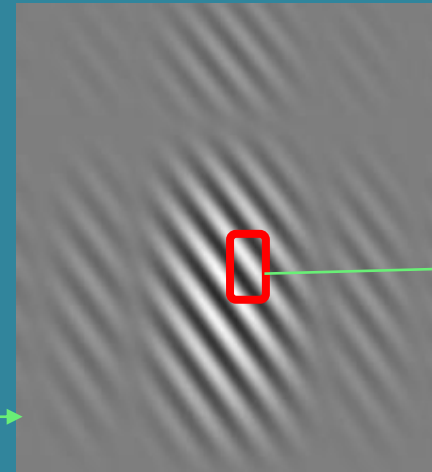
SWHM CONSISTS OF SIMPLE UNIFORM ELEMENTS



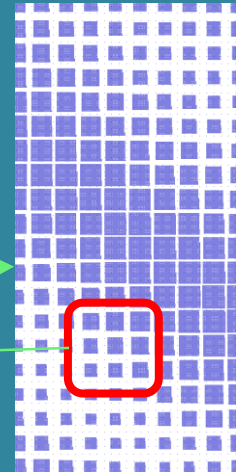
Desired topology
in Si-wafer



Corresponding SWHM

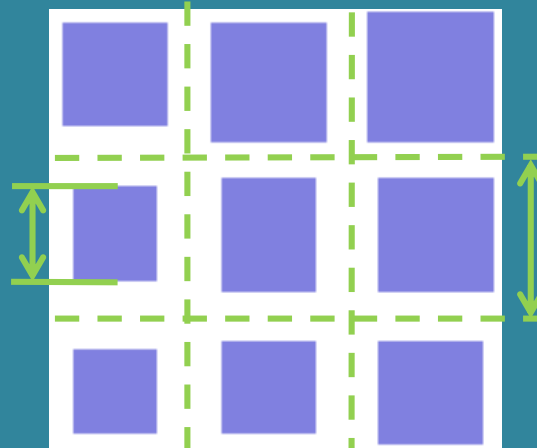


Small part of SWHM



Small part
of band

The linear size of transmission areas varies from $1,7\lambda$ to the full size of cell.



9 cells with 9 transmission
areas (TA)

The linear size of SWHM cell is constant and defined beforehand. It falls within the range $1,7 - 2,5\lambda$.

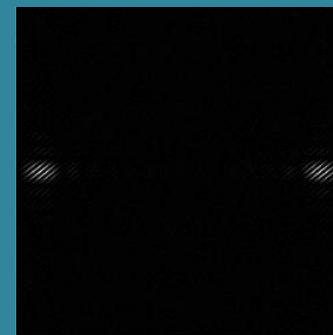
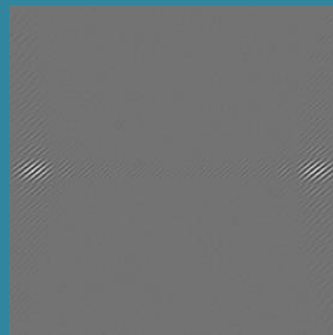
SWHM' LOCAL DEFECTS DO NOT AFFECT AERIAL IMAGE QUALITY (computer simulation)

Dust area (in %) on the SWHM (each particle $1 \mu^2$)

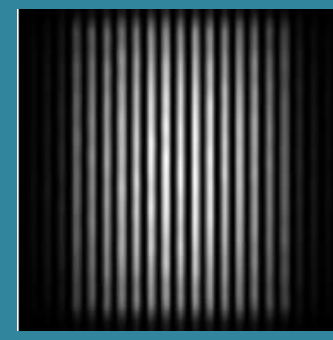
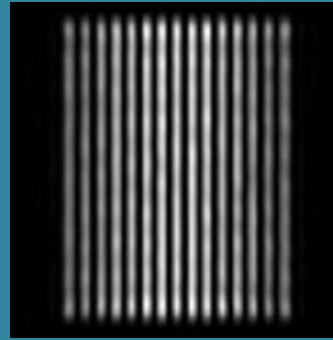
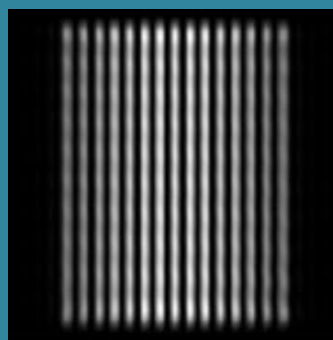
0%

45%

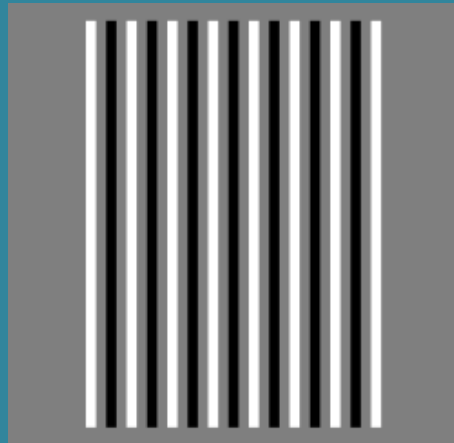
98%



SWHM



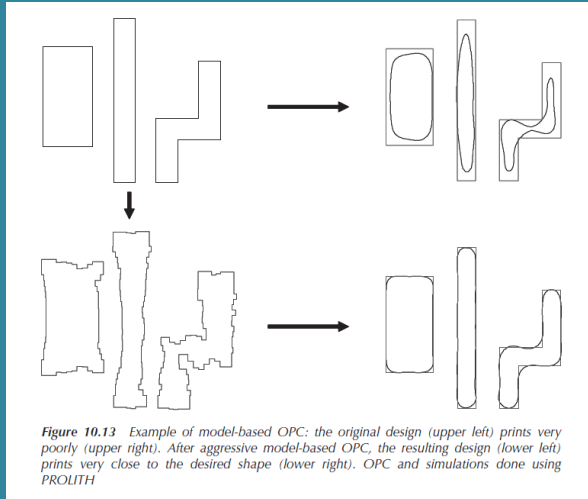
Aerial images



Initial topology
Black & white lines
indicates strong
Phase-Shift

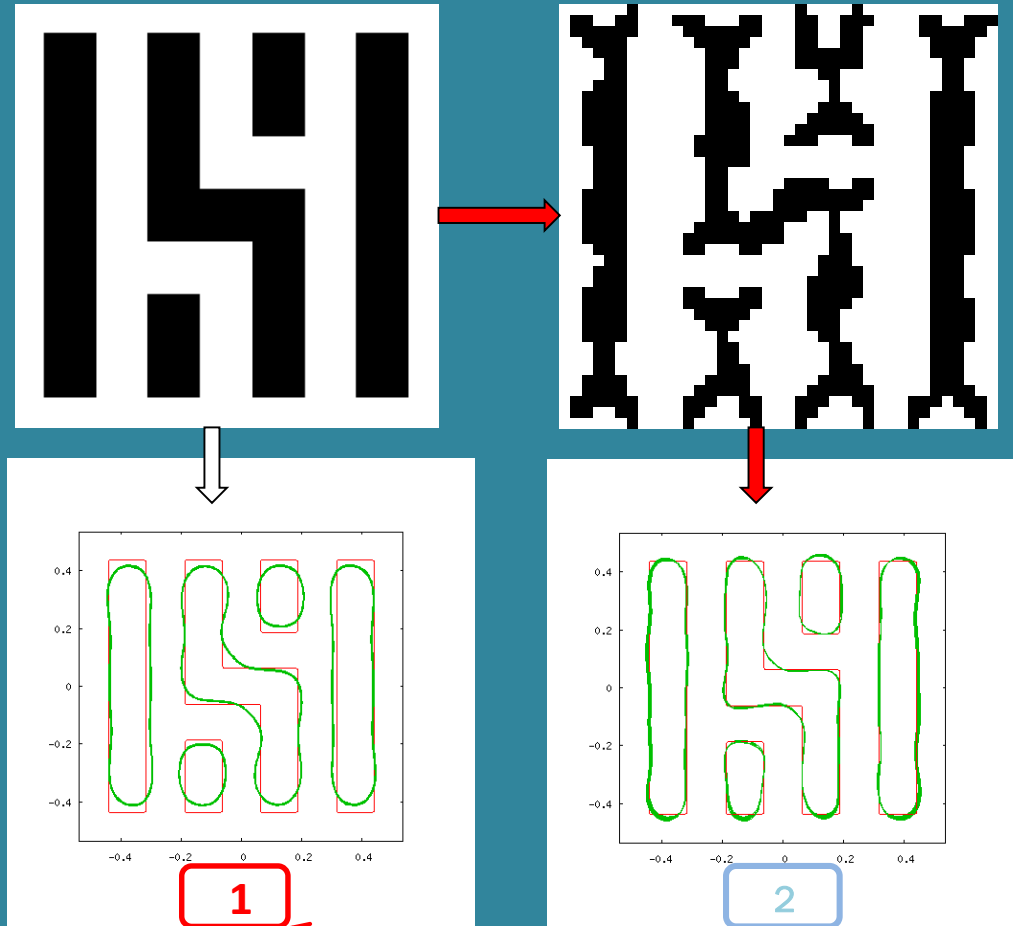
CONVENTIONAL OPC IS REPLACED WITH VIRTUAL HoloOPC

Conventional calculated & technologically produced OPC



Chris Mack,
«Fundamental Principles of Optical
Lithography: The Science of
Microfabrication»,
2009 John Wiley & Sons

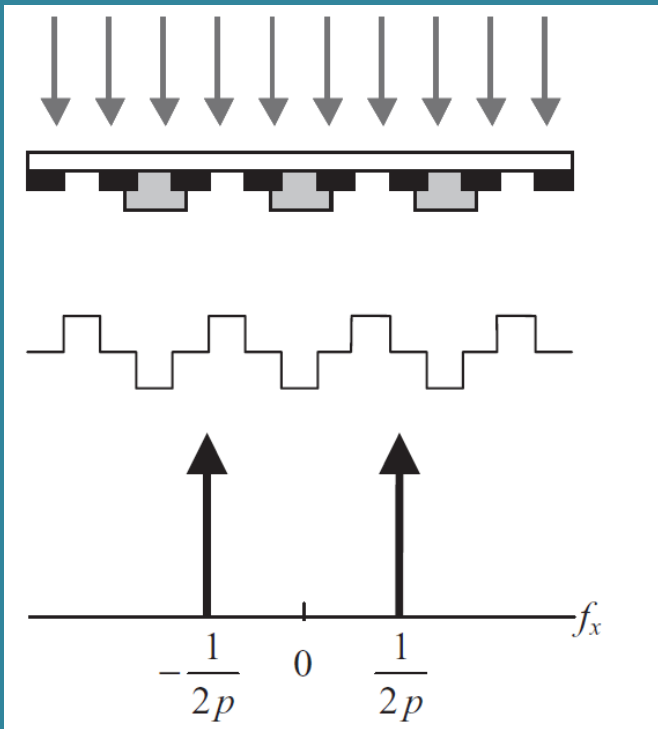
HoloOPC is realized by computation and not produced technologically



Contours of aerial image before (1) and after (2) HoloOPC

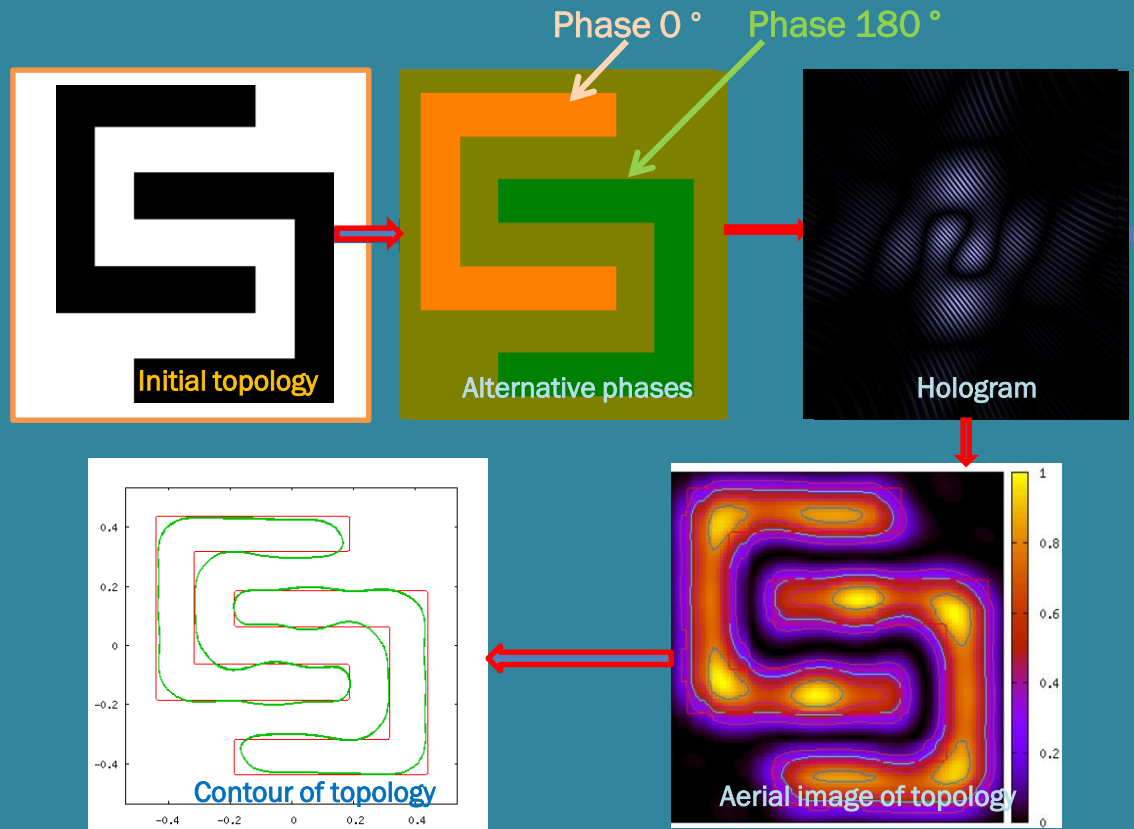
CONVENTIONAL ALTERNATIVE Phase-Shift is REPLACED with ALTERNATIVE Holo-Phase SHIFT

Conventional alternative phase-shift is realized as a technological operation



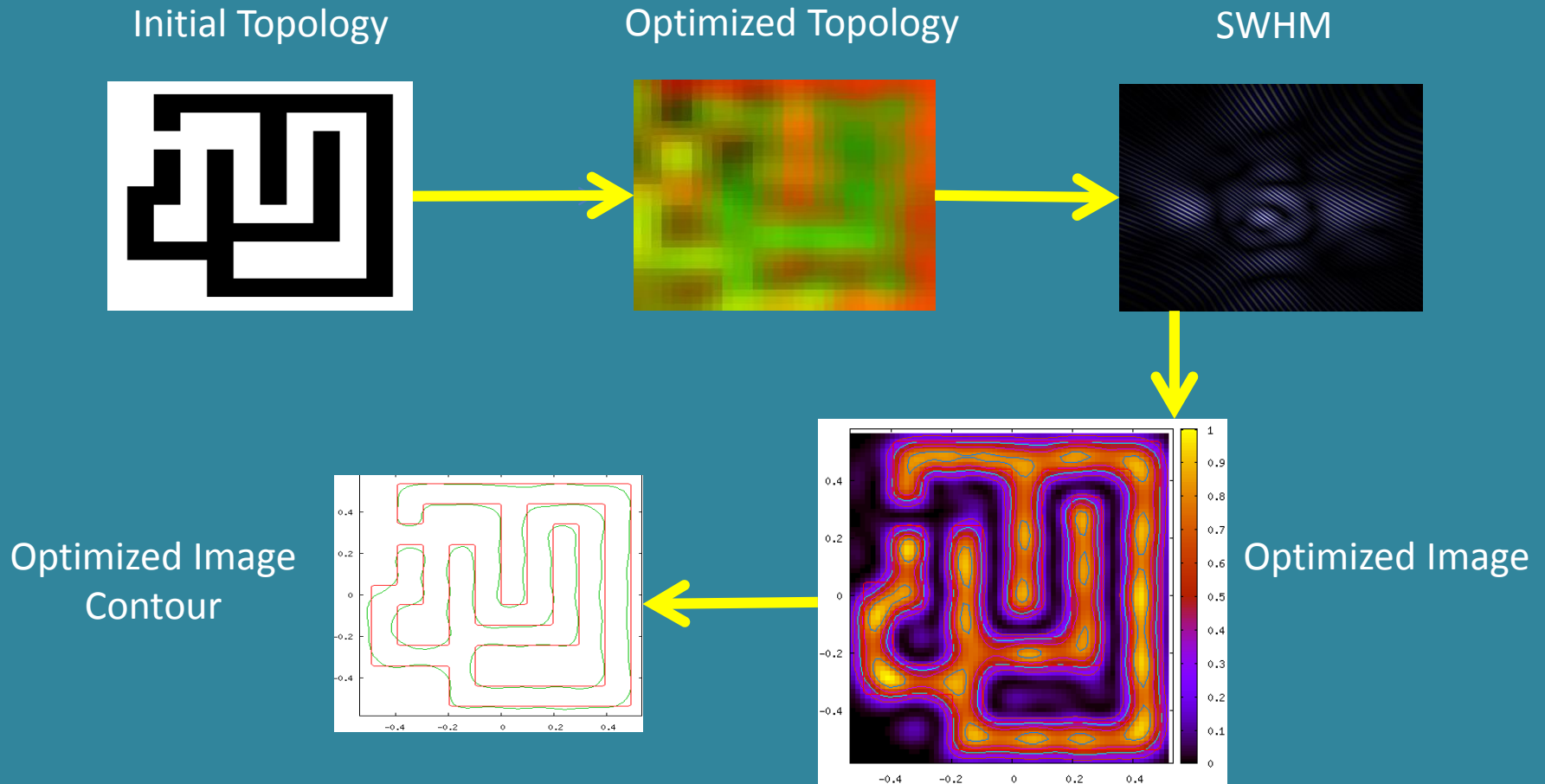
Chris Mack,
«Fundamental Principles of Optical
Lithography: The Science of Microfabrication»,
2009 John Wiley & Sons

Alternative holo phase-shift is realized by computation and does not need any technological operations



HoloOptimization

We can continuously change local values of phase & amplitude of radiation used for creation of aerial image on photo resist. With HoloOptimization' method we also can obtain topologies that are not possible to get with projection lithography.

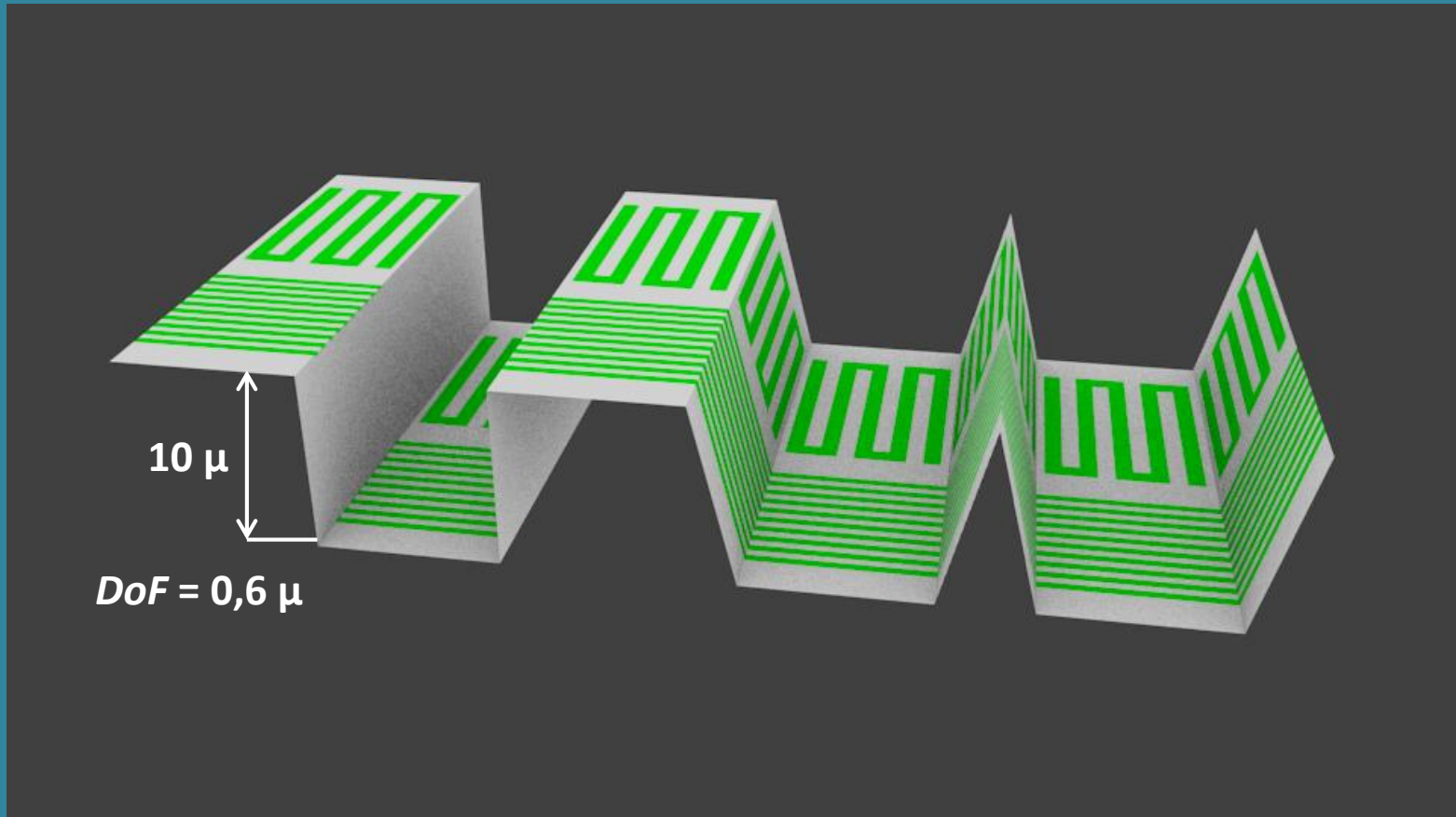


THREE PROBLEMS OF MEMS LITHOGRAPHY PRODUCING

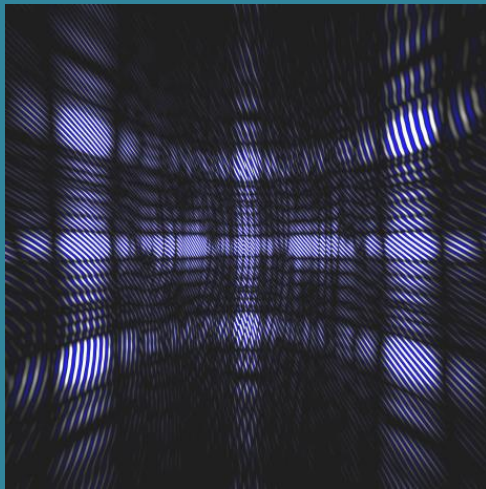
1. *Micro-relief formation* (direct electron beam etching, grey scale lithography, laser scanning with alignment system modifications)
2. *Non-planar surfaces patterning* (laser scanning with alignment system modifications, glass blowing, flexible masking, flexible membranas)
3. *Sub-wavelength complex patterns lithography* (photomasks for IC & MEMS)

**SWHL TECHNOLOGY CAN BE USEFUL
IN ALL THREE PROBLEMS SOLUTION**

3D-SWHL Lithography (Computer simulation)

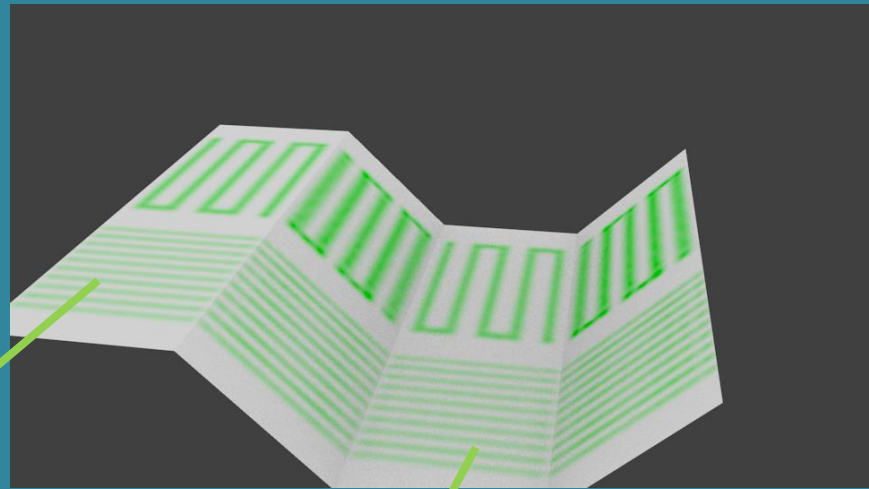


3d-Aerial image (computer simulation)

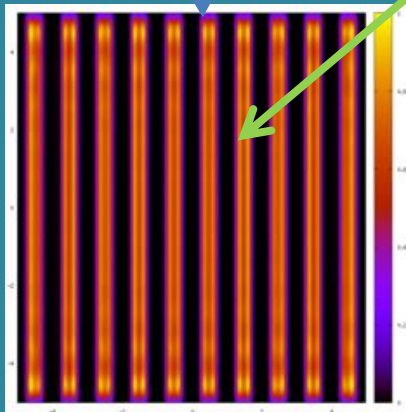


Plane hologram (SWHM)

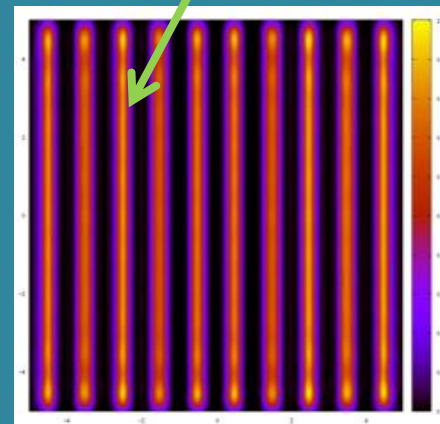
$\lambda=193\text{ nm}$
 $CD\approx 100\text{ nm}$
 $NA=?$



Reconstructed aerial image



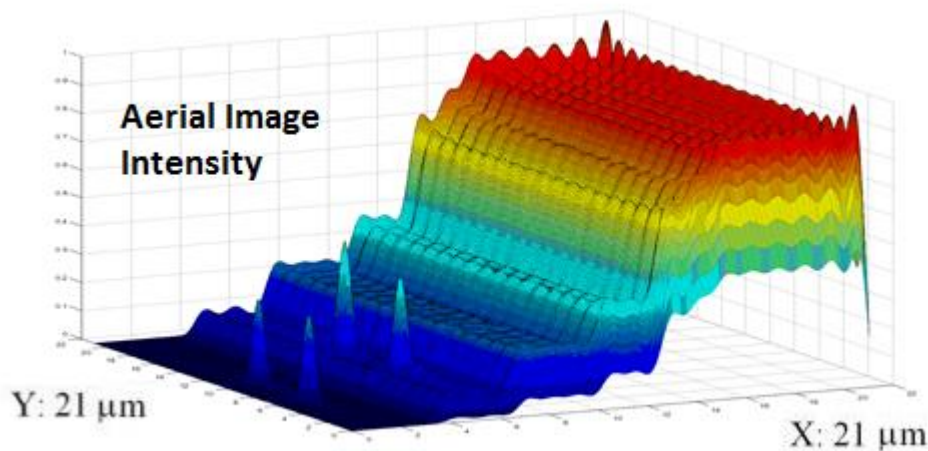
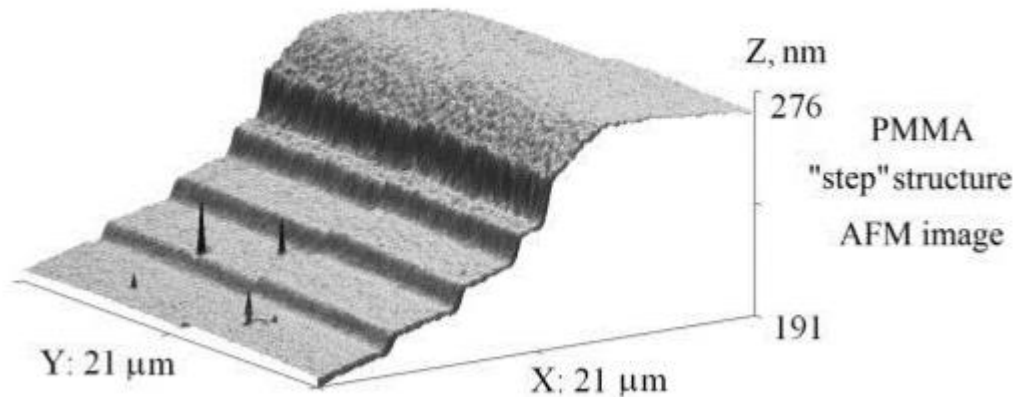
Aerial image of the
topology on upper plane



Aerial image of the
topology on lower plane

Comparison of E-Beam Lithography & SWHL lithography capabilities got by computer simulation

Graphical abstract



Relief in resist obtained with e-beam in scanning mode. Beam size is 10-15nm.

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«The new dry method of mask (relief) formation by direct electron-beam etching of resist»

^a Karpov Research Institute of Physical Chemistry, 6, Moscow 105064, Russia

^b Physics and Technology Institute of Russian Academy of Sciences,

<http://dx.doi.org/10.1016/j.mee.2013.06.03>,

Aerial image obtained with

one exposure of SWHM

(computer simulation)

$\lambda=193\text{ nm}$, $NA=0,2$